

Title of Change:	Backgrind site change from USR (onsemi Gresham) to MY2 (onsemi ISMF)
Effective date:	16 Oct 2023
Contact information:	Contact your local onsemi Sales Office or Don.Beeman@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Wafer Fab Change
Change Sub-Category(s):	Manufacturing Site Transfer

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi, ISMF Malaysia	None

Description and Purpose:

onsemi would like to notify customer of a change in backgrind location for the devices listed in this Product Bulletin. Products are currently receiving backgrind in onsemi Gresham US, but will be moved to our center of excellence for backgrind at onsemi, ISMF Malaysia. Products produced on this technology, out of this onsemi Gresham, have been backgrinding in onsemi, ISMF Malaysia for > 10 years now.

	From	To
BACKGRIND	onsemi Gresham, USA	onsemi ISMF, Malaysia

List of Affected Standard Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [**PCN Customized Portal**](#).

NCV2002SN1T1G	NCV2002SN2T1G	NCV500SN18T1G
NCV500SN28T1G	NCV500SN33T1G	NCV551SN15T1G
NCV551SN18T1G	NCV551SN25T1G	NCV551SN28T1G
NCV551SN30T1G	NCV551SN33T1G	NCV551SN36T1G
NCV551SN50T1G	NCV571MN09TBG	NCV571MN10TBG
NCV571MN12TBG	NCV7101SN1T1G	NCV7101SN2T1G
NCV8560MN150R2G	NCV8560MN330R2G	NCV8560MN500R2G
NCV8560SN130T1G	NCV8560SN180T1G	NCV8560SN250T1G
NCV8560SN280T1G	NCV8560SN330T1G	NCV8560SN350T1G
NCV8603SN33T1G	NCV8605MN18T2G	NCV8605MN25T2G
NCV8690MN33T2G	NCV8606MN50T2G	NCV8606MN30T2G
NCV8606MN25T2G	NCV8606MN15T2G	NCV8605MNADJT2G
NCV8605MN33T2G	NCV8605MN30T2G	NCV8605MN28T2G